Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type ( $L^2-\pi$ -MOSV)

## 2SK2741

# Chopper Regulator, DC-DC Converter and Motor Drive Applications

• 4 V gate drive

 $\begin{array}{ll} \bullet & Low \ drain-source \ ON \ resistance & \vdots \ RDS \ (ON) = 0.12 \ \Omega \ (typ.) \\ \bullet & High \ forward \ transfer \ admittance & \vdots \ |Y_{fs}| = 5.0 \ S \ (typ.) \\ \end{array}$ 

• Low leakage current :  $I_{DSS} = 100 \mu A \text{ (max) (V}_{DS} = 60 \text{ V)}$ 

• Enhancement-mode :  $V_{th} = 0.8 \sim 2.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$ 

#### **Maximum Ratings (Ta = 25°C)**

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	60	V	
Drain-gate voltage (Ro	<sub>SS</sub> = 20 kΩ)	$V_{DGR}$	60	٧	
Gate-source voltage		$V_{GSS}$	±20	V	
Drain current	DC (Note 1)	I <sub>D</sub>	5	Α	
	Pulse (Note 1)	I <sub>DP</sub>	20	A 	
Drain power dissipation	n (Note 2)	$P_{D}$	2.5	W	
Single pulse avalanche	e energy (Note 3)	E <sub>AS</sub>	129	mJ	
Avalanche current		I <sub>AR</sub>	5	Α	
Repetitive avalanche e	nergy (Note 4)	E <sub>AR</sub>	0.25	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature ra	ange	T <sub>stg</sub>	-55~150	°C	

# 

DRAIN (HEAT SINK)

2-7H1B

Weight: 0.12 g (typ.)

GATE

SOURCE

#### Marking

JEDEC
JEITA
TOSHIBA

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	50	°C/W



Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: Mounted on ceramic substrate (25.4 mm × 25.4 mm × 0.8 mm)

Note 3:  $V_{DD}$  = 25 V,  $T_{ch}$  = 25°C (initial), L = 7 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 5 A

Note 4: Repetitive rating; Pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device.

Please handle with caution.



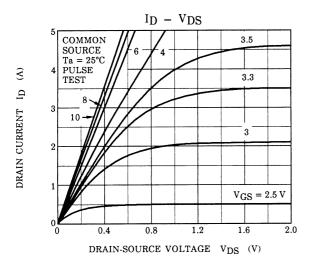
## Electrical Characteristics (Ta = 25°C)

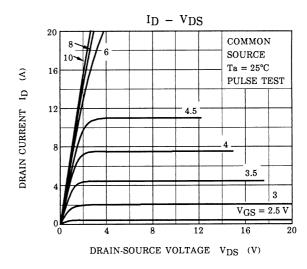
Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V		_	±10	μΑ
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V		_	100	μA
Drain-source br	eakdown voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	60	_	_	V
Gate threshold v	oltage/	$V_{th}$	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	0.8	_	2.0	V
Drain-source ON resistance		R <sub>DS (ON)</sub>	V <sub>GS</sub> = 4 V, I <sub>D</sub> = 1.3 A	_	0.20	0.30	Ω
			V <sub>GS</sub> = 10 V, I <sub>D</sub> = 2.5 A	_	0.12	0.16	
Forward transfer	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 2.5 A	3.0	5.0	_	S
Input capacitano	e	C <sub>iss</sub>		_	370	_	
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	60	_	pF
Output capacitance		Coss		_	180	_	
Switching time	Rise time	t <sub>r</sub>	$V_{GS}_{0V}$ $I_{D}=2.5A$ $R_{L}=12\Omega$ $V_{DD}=30V$	_	18	_	ns
	Turn-on time	t <sub>on</sub>		_	25	_	
	Fall time	t <sub>f</sub>		_	55	_	
	Turn-off time	t <sub>off</sub>	Duty $\leq 1\%$ , $t_{W} = 10 \mu s$	_	170	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	12	_	
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 48 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$		8	_	nC _
Gate-drain ("miller") Charge		Q <sub>gd</sub>			4	_	

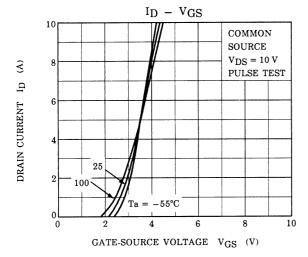
## Source-Drain Ratings and Characteristics (Ta = 25°C)

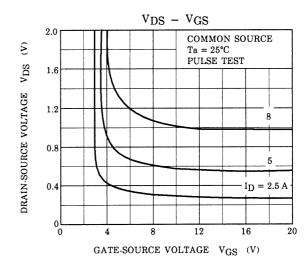
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	5	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	-	_	_	20	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 5 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 5 A, V <sub>GS</sub> = 0 V, dI <sub>DR</sub> / dt = 50 A / µs	_	70	_	ns
Reverse recovery charge	Q <sub>rr</sub>	1DR = 3 A, VGS = 0 V, αιDR / αι = 50 A / μs		0.1	_	μC

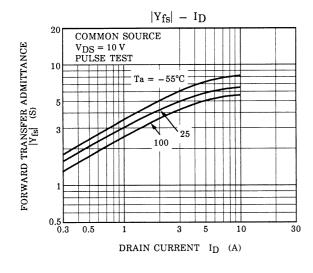
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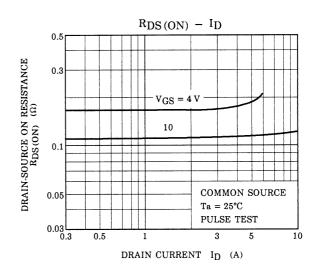




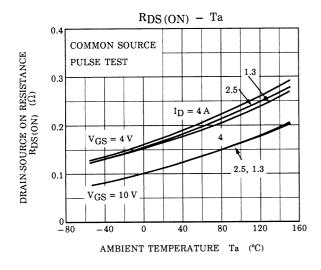


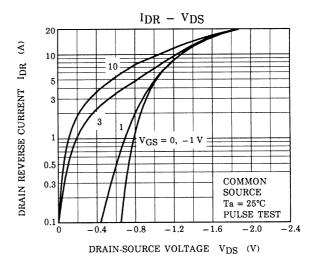


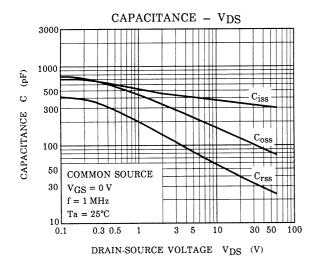


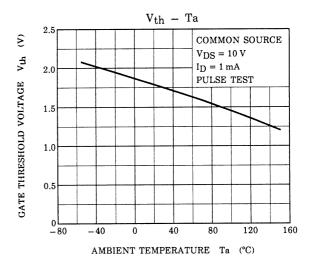


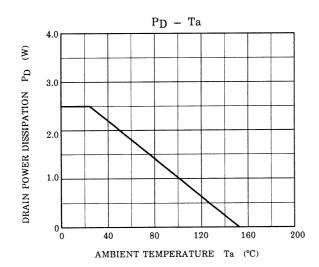
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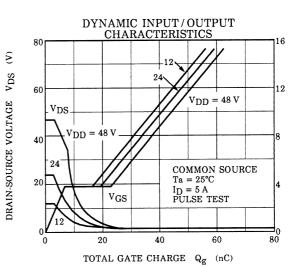




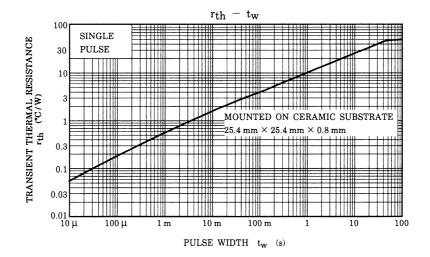


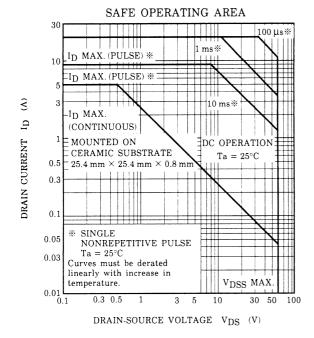


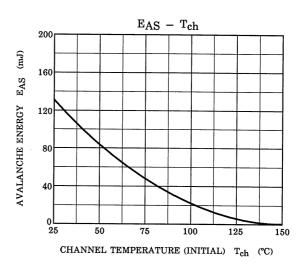


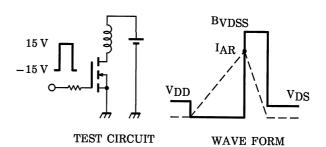


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$$R_G$$
 = 25  $\Omega$   
 $V_{DD}$  = 25 V, L = 7 mH

$$EAS = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left( \frac{BVDSS}{BVDSS - VDD} \right)$$

#### **RESTRICTIONS ON PRODUCT USE**

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